MBR0540T1G, NRVB0540T1G, MBR0540T3G, NRVB0540T3G

Schottky Power Rectifier, Surface Mount,

0.5 A, 40 V, SOD-123 Package

The Schottky Power Rectifier employs the Schottky Barrier principle with a barrier metal that produces optimal forward voltage drop−reverse current tradeoff. Ideally suited for low voltage, high frequency rectification, or as a free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package provides an alternative to the leadless 34 MELF style package.

Features

- Guardring for Stress Protection
- Very Low Forward Voltage
- Epoxy Meets UL 94 V−0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- AEC−Q101 Qualified and PPAP Capable
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb−Free*

Mechanical Characteristics

- Device Marking: B4
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C max. for 10 Seconds
- ESD Rating:
  - ♦ Human Body Model = 3B
  - ♦ Machine Model = C

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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SCHOTTKY BARRIER RECTIFIER 0.5 AMPERES, 40 VOLTS

SOD−123
CASE 425
STYLE 1

MARKING DIAGRAM

B4 = Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MBR0540T1G	SOD−123 (Pb−Free)	3,000/Tape & Reel (8 mm Tape, 7” Real)
NRVB0540T1G	SOD−123 (Pb−Free)	3,000/Tape & Reel (8 mm Tape, 7” Real)
MBR0540T3G	SOD−123 (Pb−Free)	10,000/Tape & Reel (8 mm Tape, 13” Real)
NRVB0540T3G	SOD−123 (Pb−Free)	10,000/Tape & Reel (8 mm Tape, 13” Real)

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
Average Rectified Forward Current (At Rated V_R, T_C = 115°C)	I_O	0.5	A
Peak Repetitive Forward Current (At Rated V_R, Square Wave, 20 kHz, T_C = 115°C)	I_{FRM}	1.0	A
Non−Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	5.5	A
Storage/Operating Case Temperature Range	T_{stg}, T_C	−55 to +150	°C
Operating Junction Temperature	T_J	−55 to +150	°C
Voltage Rate of Change (Rated V_R, T_J = 25°C)	dv/dt	1000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance − Junction−to−Lead (Note 1) Thermal Resistance − Junction−to−Ambient (Note 2)	R_{tjl} R_{tja}	118 206	°C/W

1. Mounted with minimum recommended pad size, PC Board FR4.
2. 1 inch square pad size (1 X 0.5 inch for each lead) on FR4 board.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 3)	v_F	**T_J = 25°C**	**T_J = 100°C**	V
(i_F = 0.5 A) (i_F = 1 A)		0.51 0.62	0.46 0.61	
Maximum Instantaneous Reverse Current (Note 3)	I_R	**T_J = 25°C**	**T_J = 100°C**	μA
(V_R = 40 V) (V_R = 20 V)		20 10	13,000 5,000	

3. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

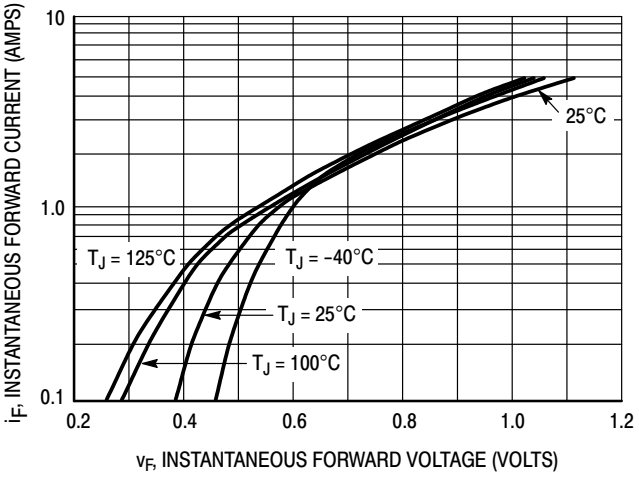


Figure 1. Typical Forward Voltage

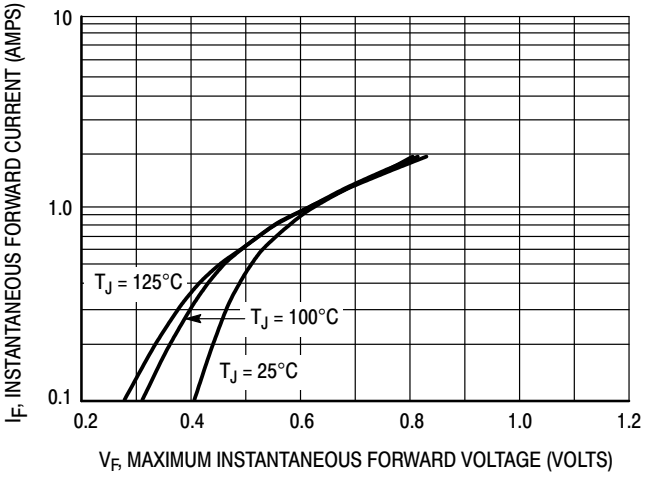


Figure 2. Maximum Forward Voltage

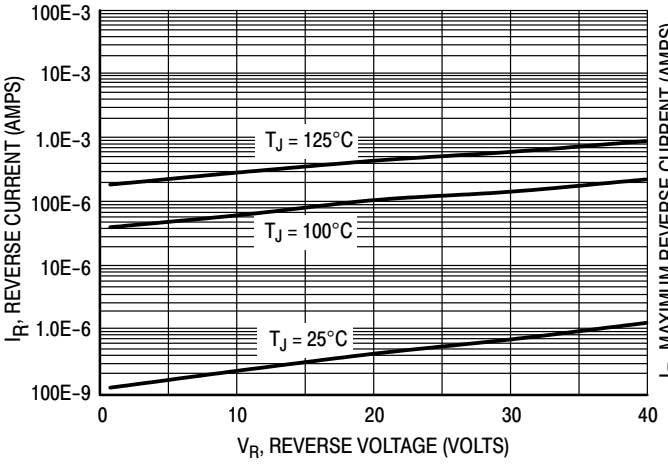


Figure 3. Typical Reverse Current

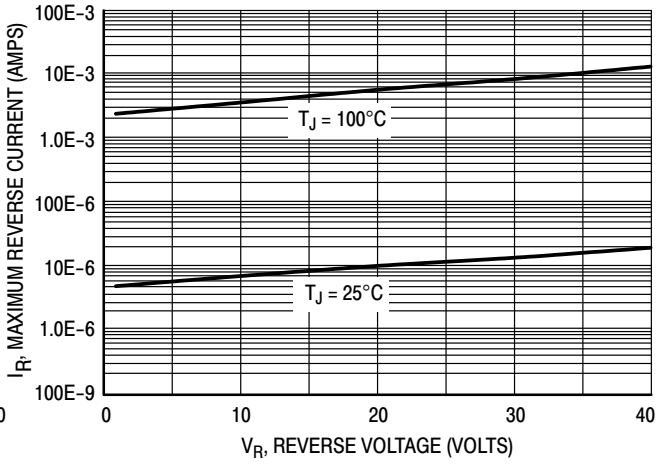


Figure 4. Maximum Reverse Current

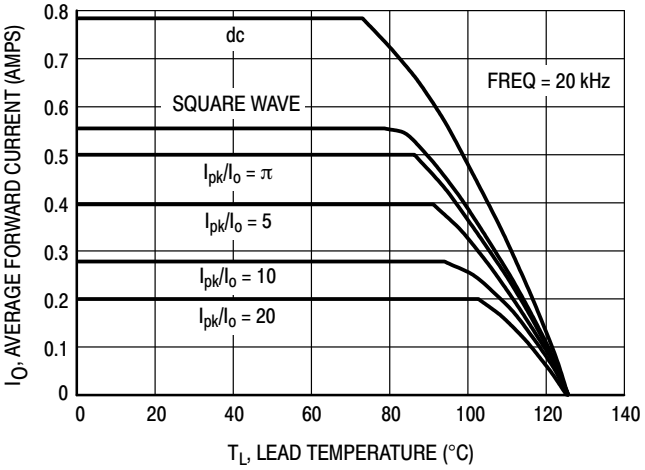


Figure 5. Current Derating

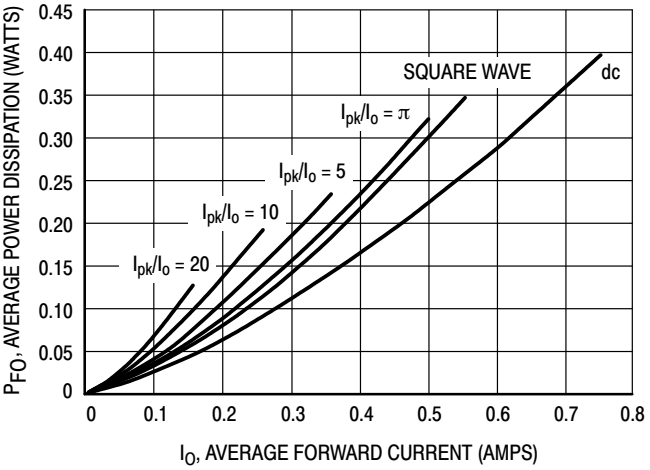


Figure 6. Forward Power Dissipation

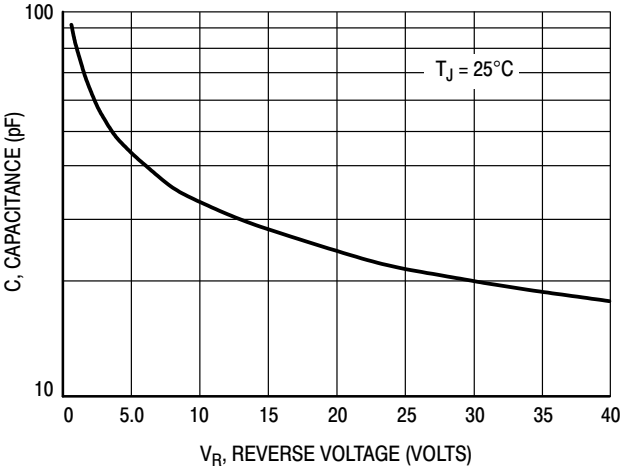


Figure 7. Capacitance

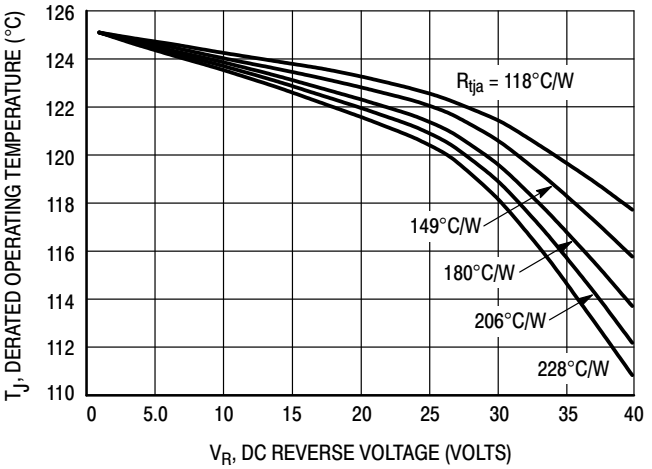


Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where

$r(t)$ = thermal impedance under given conditions,
Pf = forward power dissipation, and
Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where $r(t)$ = Rthja. For other power applications further calculations must be performed.

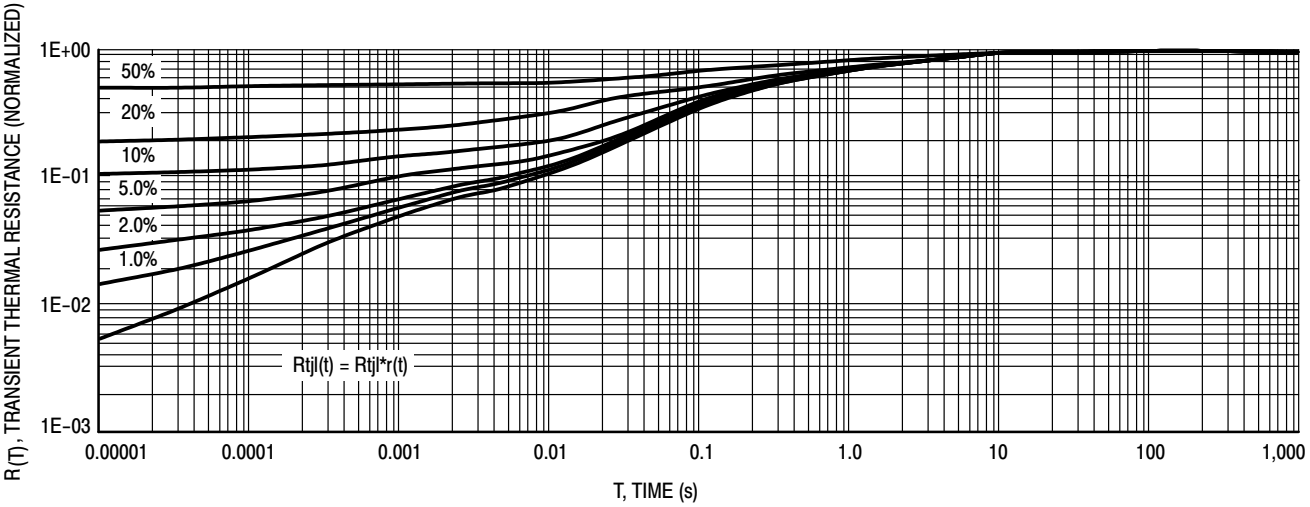


Figure 9. Thermal Response Junction to Lead

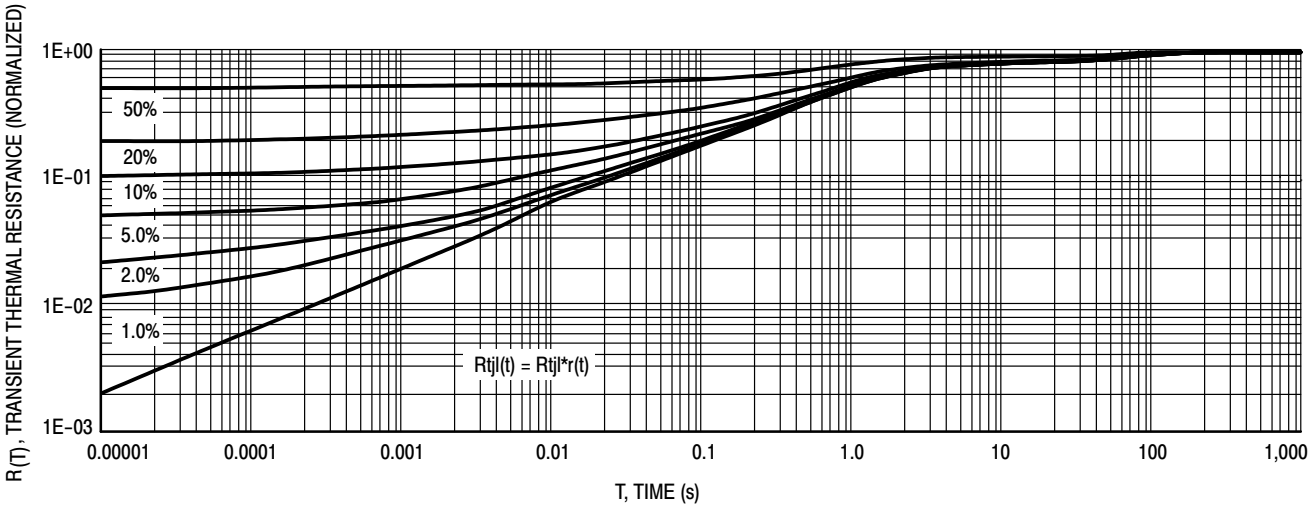


Figure 10. Thermal Response Junction to Ambient

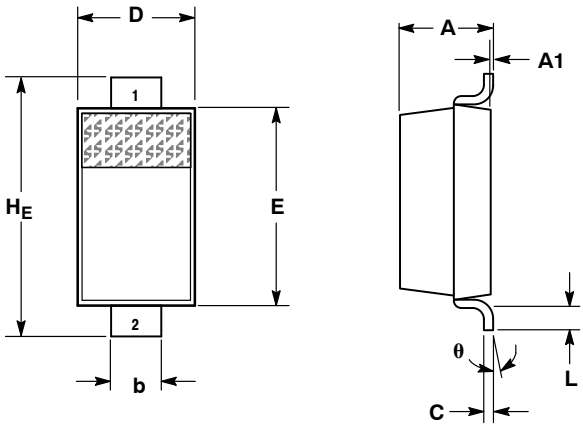
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

SCALE 5:1

SOD−123
CASE 425−04
ISSUE G

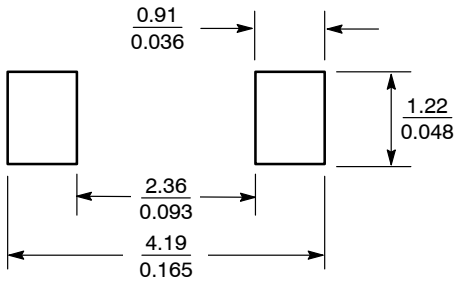
DATE 07 OCT 2009



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
c	---	---	0.15	---	---	0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
H_E	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25	---	---	0.010	---	---
θ	0°	---	10°	0°	---	10°

SOLDERING FOOTPRINT*



SCALE 10:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

STYLE 1:
PIN 1. CATHODE
2. ANODE

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DESCRIPTION:	**SOD−123**		**PAGE 1 OF 1**

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